

**46.** A method of manufacturing a microelectromechanical system (MEMS) device comprising:

forming a first reflective layer on a substrate;  
forming a sacrificial layer over the first reflective layer;  
removing a portion of the sacrificial layer to form an opening;  
filling the opening with a dielectric material to form a post;  
forming a second reflective layer over the sacrificial layer;  
removing a portion of the second reflective layer and a portion of the post to form a hole;  
filling the hole with a conductive material to form an electrode; and  
removing the sacrificial layer.

**47.** The method of claim **46**, wherein the second reflective layer is located and movable between a first position and a

second position, the second reflective layer in contact with a portion of the device when in the first position and not in contact with the portion of the device when in the second position, wherein at least a portion of the electrode is higher than the second reflective layer when the second reflective layer is in the first position.

**48.** The method of claim **47**, wherein at least a portion of the electrode is directly above at least a portion of the second reflective layer when the second reflective layer is in the first position.

**49.** The method of claim **46**, wherein the electrode is at least partially supported by the post.

**50.** A MEMS device manufactured with the method of claim **46**.

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